

Excellent Integrated System Limited

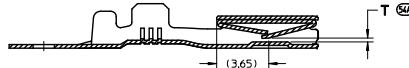
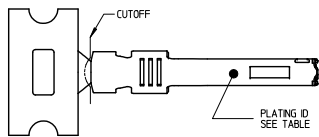
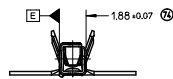
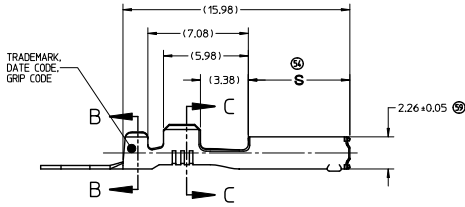
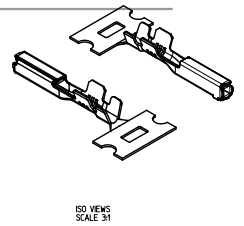
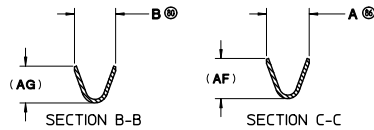
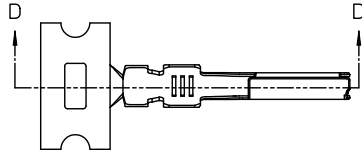
Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

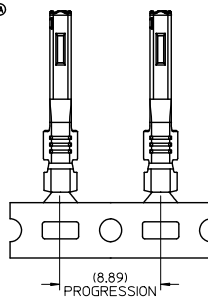
[Molex Connector Corporation](#)
[0334670006](#)

For any questions, you can email us directly:

sales@integrated-circuit.com



SECTION D-D



- NOTES: UNLESS OTHERWISE SPECIFIED
1. MATERIALS: SEE TABLE
 2. PACKAGING SPECIFICATION: PK-3500-516 AND PK-3000-759
 3. CRIMPING PER APPLICATION SPECIFICATION AS-33468-001
 4. CRIMPED LEAD MEETS THE FOLLOWING:
 - 4.1 SAE/USCAR-21 MAY 2002
 - 4.2 SAE/USCAR-21 REV. 3, APRIL 2001
 - 4.3 SAE/USCAR-12 REV. 2
 - 4.4 DPM #3791 AUGUST 22, 2000 (DRAFT)
 - TEMPERATURE CLASS 3, APPLIES ONLY TO Au PARTS
 - 4.5 DPM #3791 JANUARY, 2005
 - TEMPERATURE CLASS 3, APPLIES ONLY TO Ag PARTS
 5. PLATING NOTES:
 - 5.1 TIN PLATING (ENTIRE TERMINAL)
 - 5.1.1 ELECTRO REFLOW 190 - 330 MICROMETERS TIN OVER 0.25 - 0.76 MICROMETERS NICKEL
 - 5.2 GOLD PLATING
 - 5.2.1 UNDERPLATE OVERALL 125-225 MICROMETERS DUCTILE SULPHAMATE NICKEL
 - 5.2.2 ELECTRODEPOSITED GOLD 0.76 - 15 MICROMETERS IN CONTACT AREAS
 - 5.2.3 ELECTRODEPOSITED TIN MATTE FINISH 25 - 4.0 MICROMETERS IN CRIMP AREA
 - 5.3 SILVER PLATING
 - 5.3.1 UNDERPLATE OVERALL 125-225 MICROMETERS DUCTILE SULPHAMATE NICKEL
 - 5.3.2 ELECTRODEPOSITED PURE SILVER 99.5% PURITY SEMI-BRIGHT FINISH WITH NO BRIGHTENERS OR CHROMATES 15 - 33 MICROMETERS IN CONTACT AREAS
 - 5.3.3 ANTI-TARNISH TREATMENT FOR SILVER PLATED AREA: SYNTHETIC HYDROCARBON CONTACT SURFACE FINISH OR EQUIVALENT
 - 5.3.4 ELECTRODEPOSITED TIN MATTE FINISH 25 - 4.0 MICROMETERS IN CRIMP AREA

WIRE SIZE	GRP CODE	PART NUMBER	REEL PAYOFF DIRECTION	DM A	DM B	DM T	DM AF	DM AG	BASE MATERIAL	PLATING ID
22 AWG	A	33468-0002	D	2.3	2.3	7.15 ± 0.10	0.26 ± 0.07	0.25	COPPER ALLOY	Sn Lead Free
		33468-0001	B	2.3	2.3	6.97 ± 0.07	0.26 ± 0.07	0.25	COPPER ALLOY	Au Lead Free
		33467-0004	D	2.3	2.3	6.97 ± 0.07	0.26 ± 0.07	0.25	COPPER ALLOY	Sn Lead Free
		34736-1001	B	2.3	2.3	6.97 ± 0.07	0.26 ± 0.07	0.25	COPPER ALLOY	Au Lead Free
18/20 AWG	B	34736-0001	B	2.3	2.3	7.15 ± 0.10	0.26 ± 0.07	0.25	COPPER ALLOY	Sn Lead Free
		33468-0004	D	3.0	2.9	7.15 ± 0.10	0.26 ± 0.07	0.26	COPPER ALLOY	Au Lead Free
		33467-0006	D	3.0	2.9	6.97 ± 0.07	0.26 ± 0.07	0.26	COPPER ALLOY	Sn Lead Free
		33467-0005	B	3.0	2.9	6.97 ± 0.07	0.26 ± 0.07	0.26	COPPER ALLOY	Au Lead Free
		34736-1002	D	3.0	2.9	6.97 ± 0.07	0.26 ± 0.07	0.26	COPPER ALLOY	Sn Lead Free
		34736-2002	B	3.0	2.9	6.97 ± 0.07	0.26 ± 0.07	0.26	COPPER ALLOY	Au Lead Free

ENTER DESCRIPTION EC NO: UAU002-0459 DRAWN: FERGUSON CHKD: DRWNGFERGUSON APPR: BMOSER	DESCRIPTION 2011/11/01	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
			mm INCH		DRAWN BY P. PULLIAM	DATE 2/3/2006	MX64 SAE RECEPTACLE TERMINAL					
			4 PLACES ±--- ±---		CHECKED BY D. HEIMANI	DATE 2/3/2006						
			3 PLACES ±--- ±---		APPROVED BY		DATE					
			2 PLACES ±0.10 ±---		B. MOSER		2/3/2006	MOLEX INCORPORATED				
			1 PLACE ±0.3 ±---		MATERIAL NO.		DOCUMENT NO.	SD-33468-001				
			ANGULAR ± 3 °		SEE TABLE		SHEET NO. 1 OF 1					
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					